

	Hits	Search Text	DBs
2	13	((substrate or wafer or device or plate) same ((spray\$3 near9 coat\$4) or (nozzle near12 spray\$3) or dispens\$5) same (photoresist or resist or polyimide or cur\$4) same solution same (coat\$3 or film or form\$3 or deposit\$4)) and ((substrate or wafer or platen or device) same surface same (prim\$2 or (treat\$5 near6 solution) or treat\$4 or pre\$3treat\$4) same (nozzle or spray or dispens\$4) same (rotat\$4 or mov\$5 or spin\$4) same (speed or rate or velocit\$4) same (vary\$4 or different or chang\$4))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB
3	147	((substrate or wafer or device or plate) same ((spray\$3 near9 coat\$4) or (nozzle near12 spray\$3) or dispens\$5) same (photoresist or resist or polyimide or cur\$4) same solution same (coat\$3 or film or form\$3 or deposit\$4)) and ((substrate or wafer or platen or device) same surface same (prim\$2 or (treat\$5 near6 solution) or treat\$4 or pre\$3treat\$4) same (nozzle or spray or dispens\$4) same (rotat\$4 or mov\$5 or spin\$4)) and ((substrate or wafer) same (rotat\$4 or spin\$4 or mov\$5))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB

	Hits	Search Text	DBs
4	22	((substrate or wafer or device or plate) same ((spray\$3 near9 coat\$4) or (nozzle near12 spray\$3) or dispens\$5) same (photoresist or resist or polymide or cur\$4) same solution same (coat\$3 or film or form\$3 or deposit\$4)) and ((substrate or wafer or platen or device) same surface same (prim\$2 or (treat\$5 near6 solution) or treat\$4 or pre\$3treat\$4) same (nozzle or spray or dispens\$4) same (rotat\$4 or mov\$5 or spin\$4)) and ((substrate or wafer) same (rotat\$4 or spin\$4 or mov\$5)) and ((photoresist or resist) same negative same positive) and ((substrate or wafer or device) same (resist or photoresist) same uniform\$4 same (surface or topograph\$6 or film or layer))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB

	Hits	Search Text	DBs
5	7	((substrate or wafer or device or plate) same ((spray\$3 near9 coat\$4) or (nozzle near12 spray\$3) or dispens\$5 or discharg\$4) same (photoresist or resist or polymide or cur\$4) same solution same (coat\$3 or film or form\$3 or deposit\$4)) and ((substrate or wafer or platen or device) same surface same (prim\$2 or (treat\$5 near6 solution) or treat\$4 or pre\$3treat\$4) same (nozzle or spray or dispens\$4) same (rotat\$4 or mov\$5 or spin\$4) same (speed or rate) same (var\$5 or rang\$3 or adjust\$4)) and ((substrate or wafer) same (rotat\$4 or spin\$4 or mov\$5)) and (contact near16 angle) and (ambient or atmosphere or air or humid\$4 or environment)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB.

	Hits	Search Text	DBs
6	7	((substrate or wafer or device or plate) same ((spray\$3 near9 coat\$4) or (nozzle near12 spray\$3) or dispens\$5) same (photoresist or resist or polyimide or cur\$4) same solution same (coat\$3 or film or form\$3 or deposit\$4)) and ((substrate or wafer or platen or device) same surface same (prim\$2 or (treat\$5 near6 solution) or treat\$4 or pre\$3treat\$4) same (nozzle or spray or dispens\$4) same (rotat\$4 or mov\$5 or spin\$4)) and ((substrate or wafer) same (rotat\$4 or spin\$4 or mov\$5)) and ((resist or photoresist) same (cycl\$4hexanone or (propylene near9 glycol)) same (ketone or methyl\$4ethyl\$4ketone))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB
7	2	((("6174561") or ("5762708"))).PN.	US-PGPUB; USPAT

	Hits	Search Text	DBs
8	85	((substrate or wafer or device or plate) same ((spray\$3 near9 coat\$4) or (nozzle near12 spray\$3) or dispens\$5 or discharg\$4) same (photoresist or resist) same solution same solvent same (coat\$3 or film or form\$3 or deposit\$4) saem (deep or micron or feature)) and ((substrate or wafer or platen or device) same surface same (prim\$2 or (treat\$5 near6 solution) or treat\$4 or pre\$3treat\$4) same (nozzle or spray or dispens\$4 or discharg\$4) same (rotat\$4 or mov\$5 or spin\$4) same (solvent or solution)) and ((substrate or wafer) same (rotat\$4 or sin\$4 or mov\$5)) and ((resist or photoresist) same (negative or positive))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB
9	1	((substrate or wafer) same ((spray\$3 near9 coat\$4) or (nozzle near12 spray\$3) or dispens\$5 or discharg\$4) same (photoresist or resist) same (coat\$3 or form\$3 or deposit\$4) same (deep or micron or feature or pattern or via or trench)) and ((substrate or wafer or platen or device) same surface same (prim\$4 or (treat\$5 near6 solution) or treat\$4 or pre\$3treat\$4) same (nozzle or spray or dispens\$4 or discharg\$4) same (rotat\$4 or mov\$5 or spin\$4) same (solvent or solution)) and ((substrate or wafer) same (rotat\$4 or spin\$4 or mov\$5)) and peroxide\$9sul\$2ric	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB

	Hits	Search Text	DBs
10	2	((substrate or wafer) same ((spray\$3 near9 coat\$4) or (nozzle near12 spray\$3) or dispens\$5 or discharg\$4) same (photoresist or resist) same (coat\$3 or form\$3 or deposit\$4)) and ((substrate or wafer or platen or device) same surface same (prim\$4 or (treat\$5 near6 solution) or treat\$4 or pre\$3treat\$4) same (nozzle or spray or dispens\$4 or discharg\$4) same (rotat\$4 or mov\$5 or spin\$4)) and ((substrate or wafer) same (rotat\$4 or spin\$4 or mov\$5)) and peroxide\$9sul\$2ric	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB
11	4	((substrate or wafer or platen or device) same surface same (prim\$4 or (treat\$5 near6 solution) or treat\$4 or pre\$3treat\$4) same (nozzle or spray or dispens\$4 or discharg\$4) same (rotat\$4 or mov\$5 or spin\$4)) and ((substrate or wafer) same (rotat\$4 or spin\$4 or mov\$5)) and peroxide\$9sul\$2ric	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB

	Hits	Search Text	DBs
12	103	((substrate or wafer or device or plate) same ((spray\$3 near9 coat\$4) or (nozzle near12 spray\$3) or dispens\$5) same (photoresist or resist or polyimide or cur\$4) same solution same (coat\$3 or film or form\$3 or deposit\$4)) and ((substrate or wafer or platen or device) same surface same (prim\$2 or (treat\$5 near6 solution) or treat\$4 or pre\$3treat\$4) same (nozzle or spray or dispens\$4) same (rotat\$4 or mov\$5 or spin\$4)) and ((substrate or wafer) same (rotat\$4 or sin\$4 or mov\$5))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB
13	54	((substrate or wafer or device or plate) same ((spray\$3 near9 coat\$4) or (nozzle near12 spray\$3) or dispens\$5 or discharg\$4) same (photoresist or resist) same (coat\$3 or film or form\$3 or deposit\$4)) and ((nozzle or spray) near22 (moving or rotat\$4 or spin\$4) same uniform\$3 same (photoresist or resist)) and negative and positive	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB
14	0	((substrate or wafer or platen or device) same clean\$4 same \$4peroxide\$9sul\$2ric same (immers\$4 or dip\$4 or solution) same (time or rate or period) same ((rins\$4 or spray\$4) near16 water near16 (time or period or rate)))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB

	Hits	Search Text	DBs
15	0	((substrate or wafer or platen or device) same clean\$4 same \$4peroxide\$9sul\$2ric same (immers\$4 or dip\$4 or solution) same (time or rate or period)) and ((substrate or wafer or device or platen) same ((rins\$4 or spray\$4) near16 water near16 (time or period or rate)))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB
16	8	((substrate or wafer or platen or device) same clean\$4 same \$4peroxide\$9sul\$2ric same (immers\$4 or dip\$4 or solution) same (time or rate or period or minutes)) and ((substrate or wafer or device or platen) same ((rins\$4 or spray\$4) near16 water near16 (time or period or rate or minutes)))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB
17	8	((substrate or wafer or platen or device) same clean\$4 same \$4peroxide\$9sul\$2ric same (immers\$4 or dip\$4 or solution) same (time or rate or period or minutes)) and ((substrate or wafer or device or platen) same ((rins\$4 or spray\$4 or immers\$5 or wash\$6) near16 water near16 (time or period or rate or minutes)))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB
18	12	((substrate or wafer or platen or device) same clean\$4 same \$4peroxide\$9sul\$2ric same (immers\$4 or dip\$4 or solution) same (time or rate or period or minutes)) and ((substrate or wafer or device or platen) same (rins\$4 or spray\$4 or immers\$5 or wash\$6) same water same (time or period or rate or minutes))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB

	Hits	Search Text	DBs
19	12	((substrate or wafer or platen or device) same clean\$4 same \$4peroxide\$9sul\$2ric same (immers\$4 or dip\$4 or solution) same (time or rate or period or minutes)) and ((rins\$4 or spray\$4 or immers\$5 or wash\$6) same water same (time or period or rate or minutes))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB
20	12	((substrate or wafer or platen or device) same clean\$4 same \$4peroxide\$9sul\$2ric same (immers\$4 or dip\$4 or solution or wash\$4 or bath) same (time or rate or period or minutes)) and ((rins\$4 or spray\$4 or immers\$5 or wash\$6) same water same (time or period or rate or minutes))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB
21	16	((substrate or wafer or platen or device) same \$4peroxide\$9sul\$2ric same (immers\$4 or dip\$4 or solution or wash\$4 or bath) same (time or rate or period or minutes)) and ((rins\$4 or spray\$4 or immers\$5 or wash\$6) same water same (time or period or rate or minutes))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB